REMARKS

Claims 1-8 are pending. New claim 8 is added.

As a preliminary matter, an Information Disclosure Statement was filed on August 3, 2005. The Examiner is requested to acknowledge consideration of the IDS with the next communication.

Claims 1-3 were rejected under 35 USC §103(a) as being unpatentable over Obata et al. Presumably, the Examiner intended to also apply Hashimoto et al. as a secondary reference based on the Examiner's comments in the rejection. This rejection is respectfully traversed.

Obata et al. is cited for its disclosure of a probe. The Examiner acknowledges that Obata et al. does not disclose the claimed element supplementing unit which mounts additional elements on the multilayer wiring board under fabrication when no defect is detected by the probe. Hashimoto et al. is applied for allegedly teaching this feature, and allegedly rendering it obvious to include this feature with the probe of Obata et al.

There is no motivation or suggestion to combine the references in a manner suggested by the Examiner.

Obata et al. is related to a structural improvement of a test device for testing a printed circuit board. On the other hand, Hashimoto et al. is directed to a package technique of a card type semiconductor device, having nothing to do with testing a printed circuit board. Hashimoto et al. does not provide any teaching or suggestion of a test device. Thus, there is no reason how

or why one of ordinary skill in the art would combine the teachings of the references in a manner

which would render the claimed invention obvious.

Claims 1 to 3 of the present invention are drawn to a test apparatus which includes a

probe and an element supplementing unit, and is characterized in that in each step of a process of

fabricating a multilayer wiring board, the probe tests each newly added component and the

wiring board is fixed or disposed of by the element supplementing unit when defects are

detected. Only when defects are not detected, another component is added to proceed with

fabrication of the multilayer wiring board.

Because Obata and Hashimoto are directed to completely different subject matter, there is

no motivation of combining the teachings of these two references as stated by the Examiner, and

even if the two references are combined, it cannot result in the advantages of the present

invention.

The Examiner argues that it would have been obvious that after testing the printed wiring

board, additional electronic compounds will be added. Thus, it appears that the Examiner does

not understand that the claimed invention requires that the test apparatus itself include the

claimed element supplementing unit. A combination of the prior art does not teach all of the

claimed elements.

For at least the foregoing reasons, the claimed invention distinguishes over the cited art

and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

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Amendment

Serial No. 10/664,930

Attorney Docket No. 021385B

Should the Examiner deem that any further action by applicant would be desirable to

place the application in condition for allowance, the Examiner is encouraged to telephone

applicant's undersigned attorney.

If this paper is not timely filed, Applicant respectfully petitions for an appropriate

extension of time. The fees for such an extension or any other fees that may be due with respect

to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

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